



ISM 868 MHz Ceramic Chip Antenna Model: AA701 TELA chip antenna Product Number: H2U64U1H2B0200

REFERENCE SPECIFICATION

Unique Electronics You Need

Version: 10705A\_rev-L

Introduction Electrical Characteristics

**Radiation Pattern** 

Layout

Tuning

Packing

Notes

#### **Table of Contents**

1	Inti	roduction	3
2	Ele	ectrical Characteristics	4
	2.1	Table with electrical properties:	4
	2.2	Return Loss (S <sub>11</sub> )	5
	2.3	VSWR (S <sub>11</sub> )	5
	2.4	Efficiency Table	6
	2.5	Efficiency vs. Frequency	6
	2.6	Radiation Pattern (with 80x40mm <sup>2</sup> Evaluation Board)	7
3	Lay	yout	8
	3.1	Antenna Dimensions	8
	3.2	Evaluation Board with Antenna	9
	3.3	Solder Land Pattern	10
4	Fre	equency tuning	11
	4.1	Reference for frequency tuning element	12
5	Pa	cking	13
6	No	tes	14
	6.1	Typical Soldering Profile for Lead-free Process	14
	6.2	Operating and storage conditions:	15
	6.3	Installation guide:	15
	6.4	Reminders for users of Unictron's AA701 ceramic chin antennas	15

**Electrical Characteristics** 

**Radiation Pattern** 

Layout

Tuning

Packing

Notes

## 1 Introduction

Unictron's AA701 ceramic chip antenna is designed for ISM 868MHz band applications, covering frequencies 863~870 MHz. Fabricated with proprietary design and processes, AA701 shows excellent performance and is fully compatible with SMT processes which can decrease the assembly cost and improve device's quality and consistency.

#### **Features**

- \* Stable and reliable in performances
- \* Low profile, compact size
- \* RoHS compliance
- \* SMT processes compatible

### **Applications**

- \* Short Range Devices (SRD)
- \* IoT applications
- \*Alarm system

**Electrical Characteristics** 

**Radiation Pattern** 

Layout

Tuning

Packing

Notes

# 2 Electrical Characteristics

## 2.1 Table with electrical properties:

Characteristics		Specifications	Unit	
Outline Dimensi	ons	5.0 x 3.0 x 0.5	mm	
Ground Plane Di	mensions	80x40	mm	
Working Frequency		863~870	MHz	
VSWR (@center fi	requency)*	2 Max.		
Characteristic Impedance		50	Ω	
Polarization		Linear Polarization		
Peak Gain			dBi	
Efficiency	( @868 MHz)	49 (typical)	%	

<sup>\*</sup>Center frequency means the frequency with the lowest value in return loss of the chip antenna on the evaluation board.

**Electrical Characteristics** 

**Radiation Pattern** 

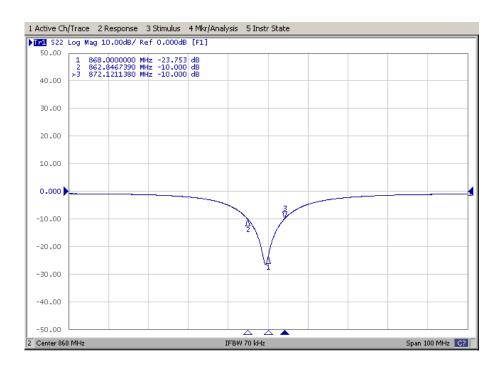
Layout

Tuning

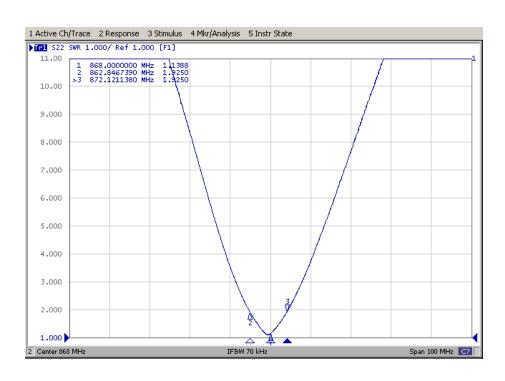
Packing

Notes

## 2.2 Return Loss (S<sub>11</sub>)



## 2.3 VSWR (S<sub>11</sub>)



**Electrical Characteristics** 

**Radiation Pattern** 

Layout

Packing

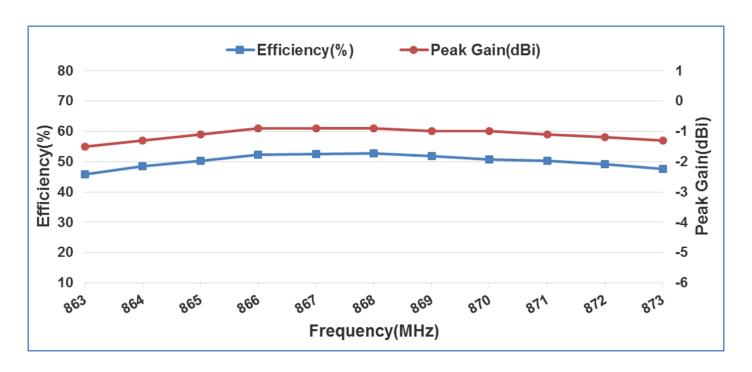
Tuning

Notes

### 2.4 Efficiency Table

Frequency(MHz)	863	864	865	866	867	868	869	870	871	872	873
Efficiency(dB)	-3.4	-3.2	-3.0	-2.8	-2.8	-2.8	-2.9	-2.9	-3.0	-3.1	-3.2
Efficiency(%)	45.9	48.4	50.3	52.2	52.5	52.8	51.8	50.8	50.3	49.2	47.7
Gain(dBi)	-1.5	-1.3	-1.1	-0.9	-0.9	-0.9	-1.0	-1.0	-1.1	-1.2	-1.3

## 2.5 Efficiency vs. Frequency



**Electrical Characteristics** 

**Radiation Pattern** 

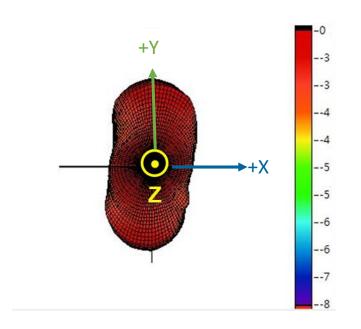
Layout

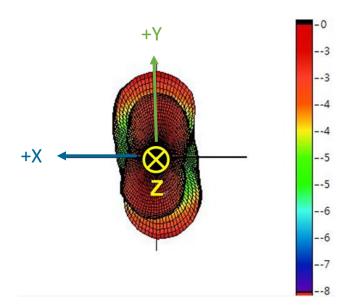
Tuning Packing

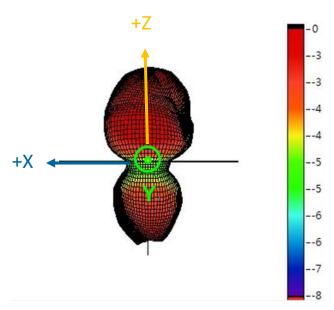
Notes

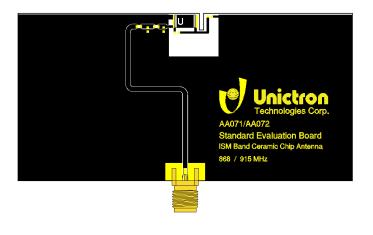
## 2.6 Radiation Pattern (with 80x40mm<sup>2</sup> Evaluation Board)

3D Gain Pattern @ 868 MHz (unit: dBi)









Introduction | Electrical Characteristics

**Radiation Pattern** 

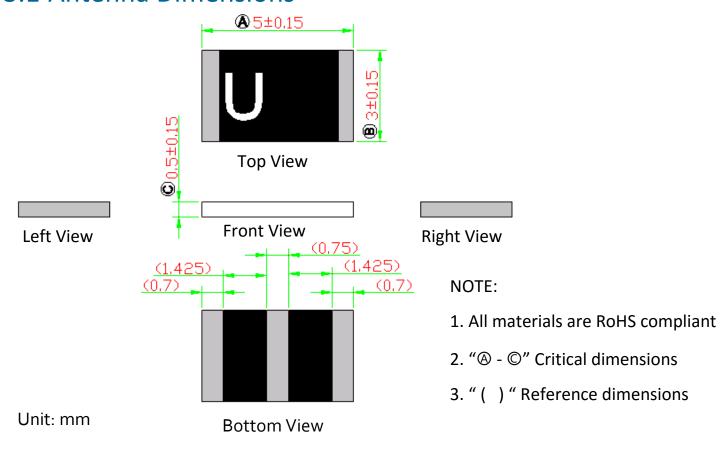
Layout

Tuning Packing

Notes

# 3 Layout

#### 3.1 Antenna Dimensions



#### **PIN Definitions**



PIN	1	2	3
Soldering Pad	Signal	Tuning/Ground	N/C

Introduction | Electrical Characteristics

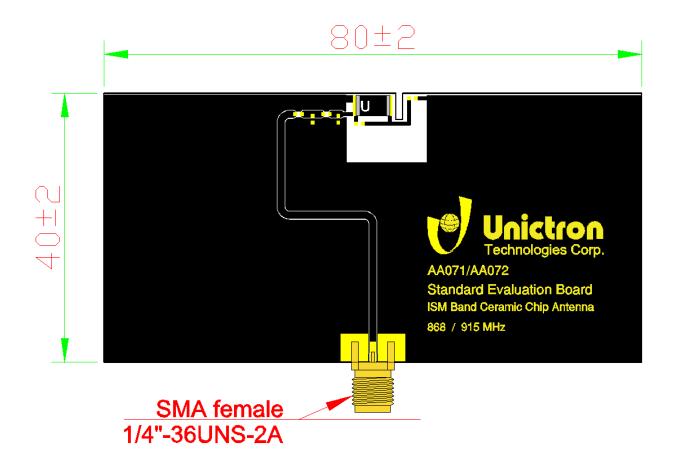
**Radiation Pattern** 

Layout

Tuning Packing

Notes

#### 3.2 Evaluation Board with Antenna



Unit: mm

**Electrical Characteristics** 

**Radiation Pattern** 

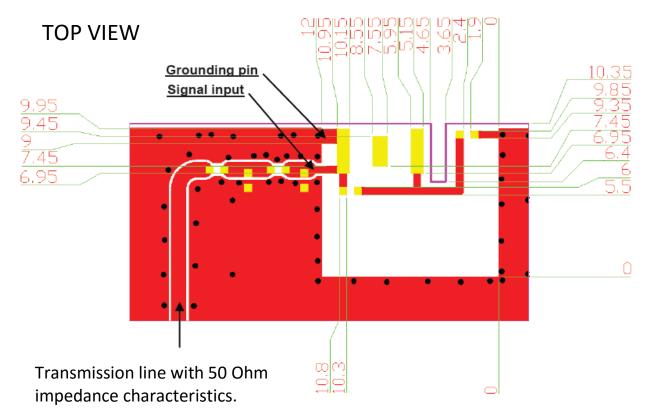
Layout

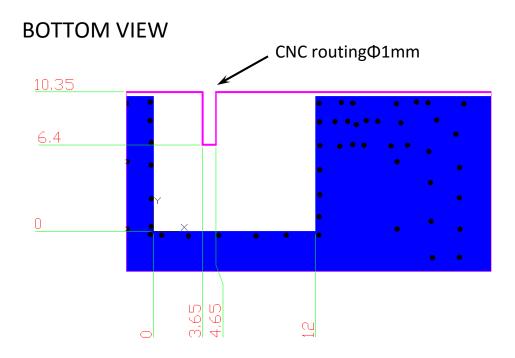
Tuning Packing

Notes

#### 3.3 Solder Land Pattern

The solder land pattern (gold marking areas) is shown below. Recommendation on matching circuit will be provided according to customer's installation conditions.





**Electrical Characteristics** 

**Radiation Pattern** 

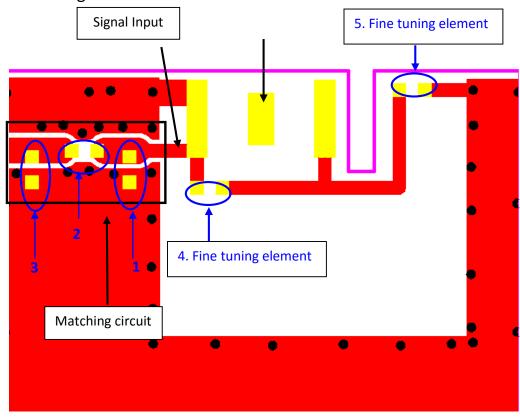
Layout

Tuning Packing

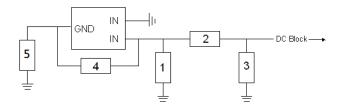
Notes

# 4 Frequency tuning

#### Chip antenna tuning scenario



With the following recommended values of matching and tuning components, the center frequencies will be about 868 MHz at out standard 80x40 mm<sup>2</sup> evaluation board.



System M				
Location	Description	Vendor	Tolerance	
1	N/A	-	-	
2	0Ω, (0402)	-	-	
3	12 nH,(0402)	Murata	5%	
4 Fine tuning element	2.7 pF,(0402)	Murata	±0.05pF	
5 Fine tuning element	2.7 pF,(0402)	Murata	±0.05pF	

**Electrical Characteristics** 

**Radiation Pattern** 

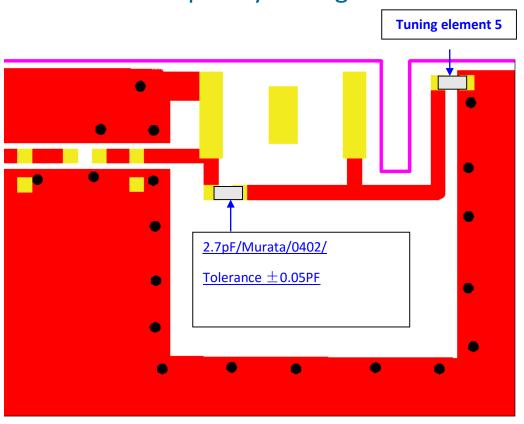
Layout

Tuning Packing

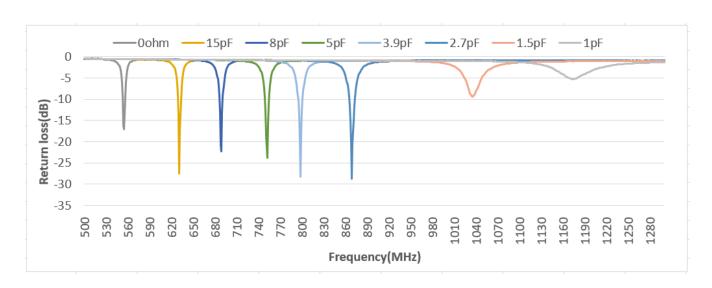
Notes

If you are using a PCB board of different dimensions, the values of suitable matching and tuning components may differ. Feel free to contact a Unictron's representative at e-sales@unictron.com for further assistance adjusting these components, optimizing PCB layout and antenna's performance.

#### 4.1 Reference for frequency tuning element



Frequencies vs. capacitance of tuning element 5



**Electrical Characteristics** 

Radiation Pattern

Layout

Tuning

Packing

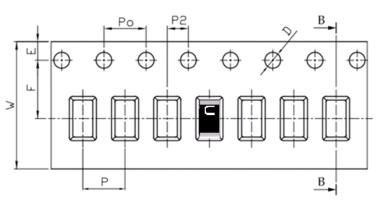
Notes

# **Packing**

1. Quantity/Reel: 6000 pcs/Reel

2. Plastic tape:

a) Tape drawing:



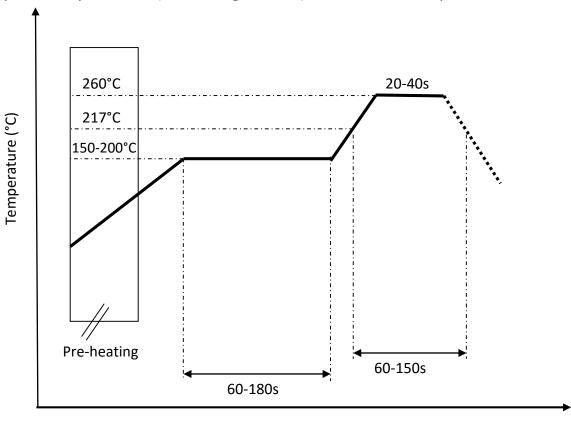
b) Tape dimensions (unit: mm)

Feature	Specifications	Tolerances
W	12.00	±0.30
Р	8.00	±0.10
Е	1.75	±0.10
F	5.50	±0.10
P2	2.00	±0.10
D	1.20	+0.10 -0.00
Po	4.00	±0.10
10Po	40.00	±0.20

# 5 Notes

## 5.1 Typical Soldering Profile for Lead-free Process

Solder paste alloy: SAC305 (Sn96.5/Ag3/Cu0.5) Lead Free solder paste



Time (s.)

**Electrical Characteristics** 

**Radiation Pattern** 

Layout

Tuning Packing

Notes

#### 5.2 Operating and storage conditions:

Operating: Storage:

Maximum Input Power: 2W Storage Temperature -5°C to +40°C

Operating Temperature: -40°C to +85°C Relative Humidity: 20% to 70%

Shelf Life: 1 year

#### 5.3 Installation guide:

Request Unictron's application notes "General guidelines for the installation of Unictron's chip antennas" for further information at e-sales@unictron.com.

# 5.4 Reminders for users of Unictron's AA701 ceramic chip antennas

- 6.4.1. This chip antenna is made of ceramic materials which are relatively more rigid and brittle compared to printed circuit board materials. Bending of circuit board at the locations where chip antenna is mounted may cause the cracking of solder joints or antenna itself.
- 6.4.2. Punching/cutting of the break-off tab of PCB panel may cause severe bending of the circuit board which may result in cracking of solder joints or chip antenna itself. Therefore break-off tab shall be located away from the installation site of chip antenna.
- 6.4.3. Be cautious when ultrasonic welding process needs to be used near the locations where chip antennas are installed. Strong ultrasonic vibration may cause the cracking of chip antenna solder joints.

**Packing** 



Introduction

**Electrical Characteristics** 

**Radiation Pattern** 

Layout

Tel: +886-3-547-5550

Tuning

Notes

Presented data were measured on reference PCB (ground) as shown in this specification. When the antenna placement or size of the PCB is changed, antenna performance and values of matching components may differ from data shown here.

Information presented in this Reference Specification is believed to be correct as of the date of publishing. Unictron Technologies Corporation reserves the rights to change the Reference Specification without notice due to technical improvements, etc. Please consult with Unictron's engineering team about the latest information before using this product. Per request, we may provide advice and assistance in implementing this antenna to a customer's device by simulation or real measurement of the interested device in our testing facilities.

#### **Unictron Technologies Corporation**

No. 41 Shuei-Keng, Guan-Si

Hsinchu 30648 Email: e-sales@unictron.com

Taiwan (R.O.C.) Web: www.unictron.com